

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

Advanced SGT Technology

Excellent  $R_{DS(ON)}$

Low gate charge

#### 1.2 Applications

DC/DC Converter

LED Backlighting

Power Management Switches

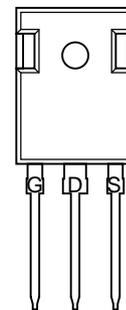
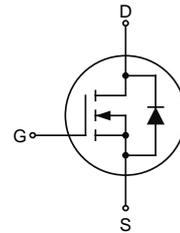
#### 1.3 Quick reference

$V_{DS}=150$  V

$I_D=260$  A

$P_D=326$  W

$R_{DS(ON)} \leq 5.8$  m $\Omega$ @ $V_{GS}=10$  V (Type:4.8 m $\Omega$ )



Top View  
TO-247

### 2. Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ260N15P	TO-247	KJ260N15P	-	-	1000

### 3. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current ( $T_C=25^\circ\text{C}$ )	260	A
$I_D$	Continuous Drain Current ( $T_C=100^\circ\text{C}$ )	185	A
$I_{DM}$	Pulsed Drain Current	720	A
$I_{AS}$	Avalanche Current	64	A
$E_{AS}$	Single Pulse Avalanche Energy	1764	mJ
$P_D$	Power Dissipation ( $T_C=25^\circ\text{C}$ ) <sup>4</sup>	326	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction-Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction-Case	0.46	$^\circ\text{C}/\text{W}$

## 4. Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>DS</sub> =250 μA	150	165	-	V
Zero Gate Voltage Source Current	I <sub>BSS</sub>	V <sub>DS</sub> =140 V, V <sub>GS</sub> =0 V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20 V, V <sub>DS</sub> =0 V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250 μA	2.0	2.9	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =40 A	-	4.8	5.8	mΩ
Forward Transconductance	G <sub>FS</sub>	V <sub>DS</sub> =5 V, V <sub>GS</sub> =15 A		33	-	S
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	V <sub>SD</sub>	I <sub>SD</sub> =20 A, V <sub>GS</sub> =0 V	-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>DS</sub> =20 A, V <sub>GS</sub> =0 V, dI <sub>SD</sub> /dt=500 A/μs	-	101	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	1240	-	nC
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0 V, V <sub>DS</sub> =25 V, Frequency=1 MHz	-	4200	-	pF
Output Capacitance	C <sub>oss</sub>		-	2867	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	215	-	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =75 V, V <sub>GEN</sub> =10 V, R <sub>G</sub> =3 Ω, R <sub>L</sub> =1.07 Ω,	-	18	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	22	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	35	-	
Turn-off Fall Time	t <sub>f</sub>		-	10	-	
<b>Gate Charge Characteristics</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10 V, V <sub>DS</sub> =75 V, I <sub>DS</sub> =70 A	-	65	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	20	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	19	-	

Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2 OZ copper.
- The test condition is Pulse Test: Pulse width ≤ 300 μs, Duty Cycle ≤ 2%.
- The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=0.5 mH, I<sub>AS</sub>=64 A
- The power dissipation is limited by 150°C junction temperature.
- The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

## 7. Typical Characteristics

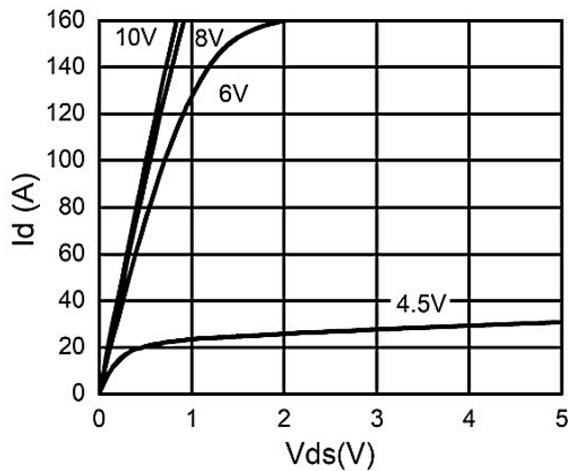


Figure 1. Output Characteristics

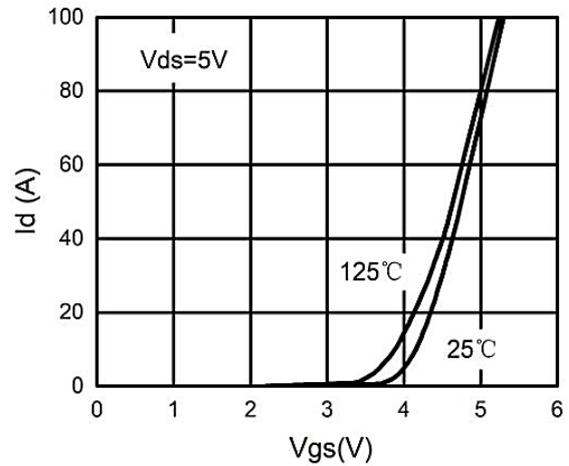


Figure 2. Transfer Characteristics

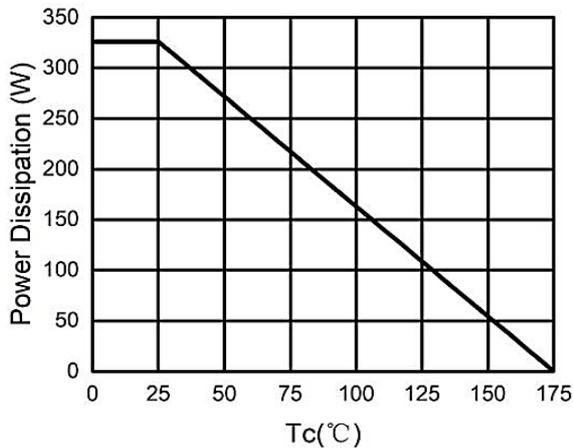


Figure 3. Power Dissipation

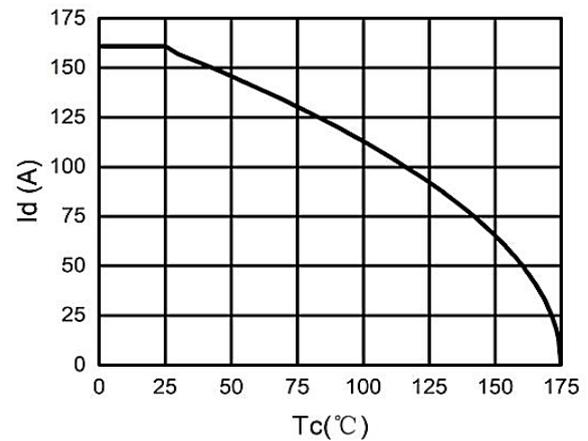


Figure 4. Drain Current

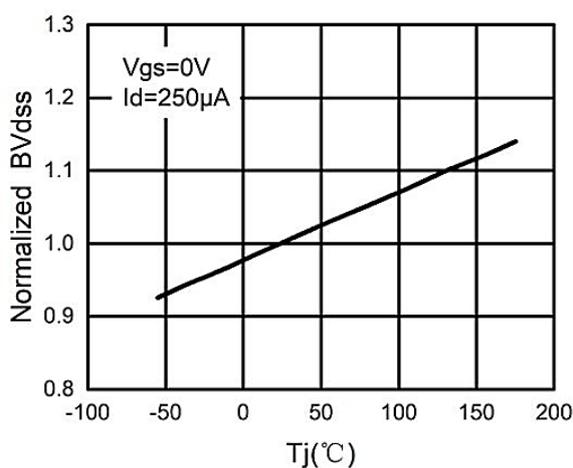


Figure 5. BVDSS vs Junction Temperature

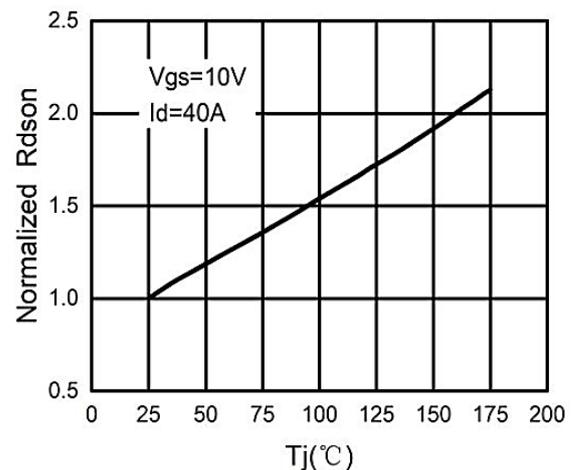


Figure 6. RDS(ON) vs Junction Temperature

## 7. Typical Characteristics (cont.)

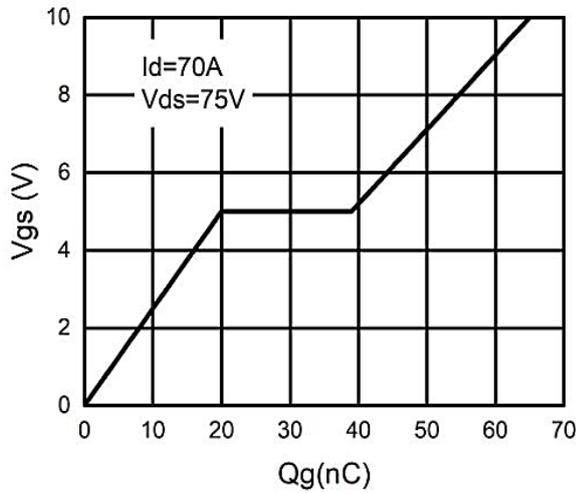


Figure 7. Gate Charge Waveforms

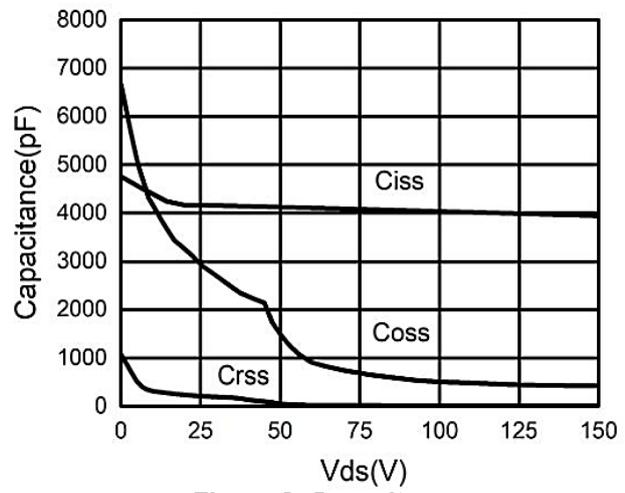


Figure 8. Capacitance

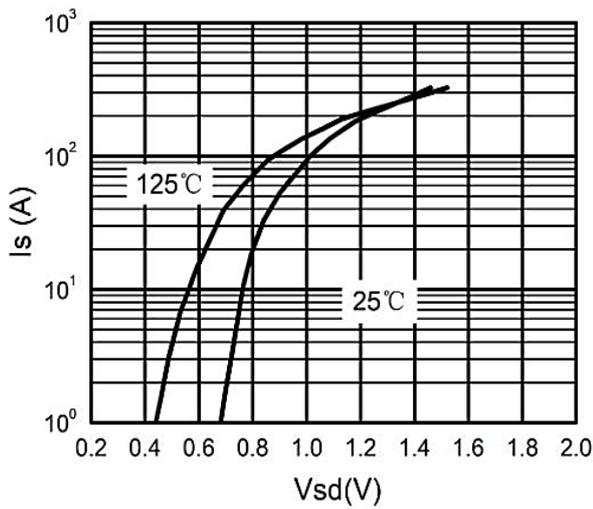


Figure 9. Body-Diode Characteristics

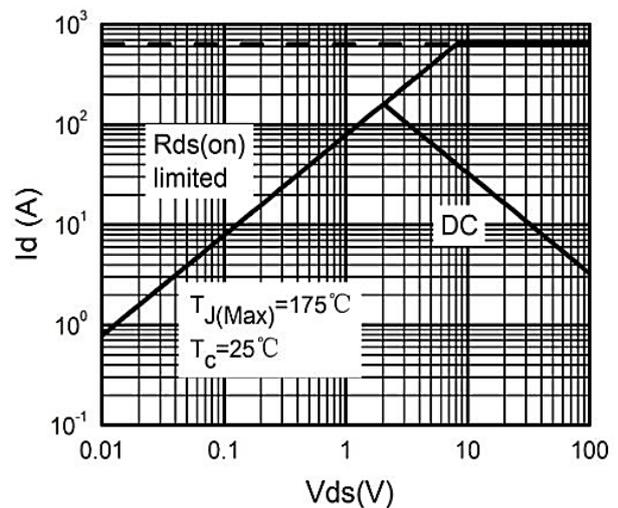


Figure 10. Maximum Safe Operating Area

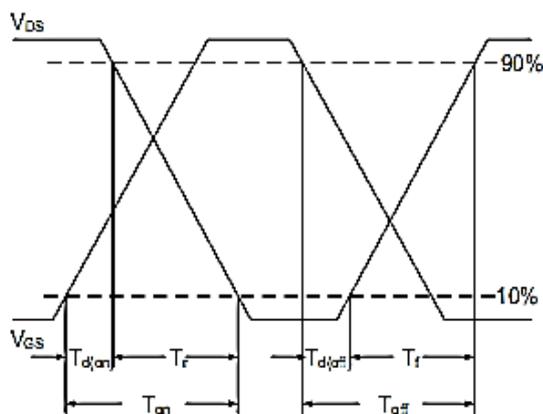


Figure 11. Switching Time Waveform

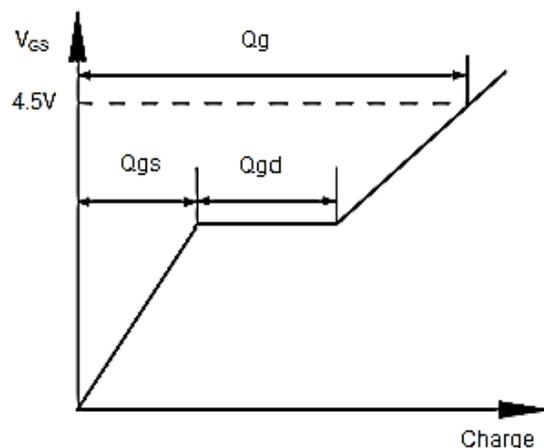
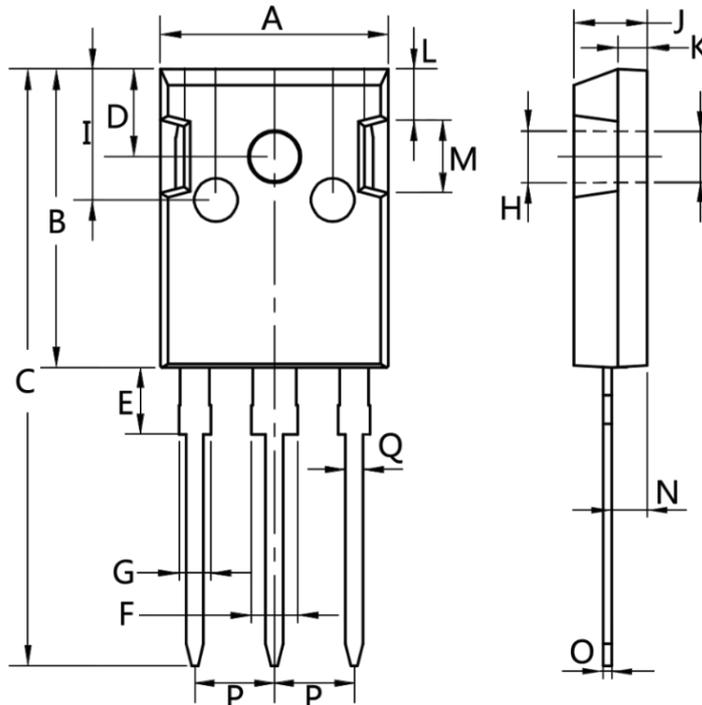


Figure 12. Gate Charge Waveform

## 8. Package Dimensions

### TO-247 Package



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	MIN.	MAX.	MIN.	MAX.
A	15.00	16.00	0.5906	0.6299
B	20.00	21.00	0.7874	0.8268
C	41.00	42.00	1.6142	1.6535
D	5.00	6.00	0.1969	0.2362
E	4.00	5.00	0.1575	0.1969
F	2.50	3.50	0.0984	0.1378
G	1.75	2.50	0.0689	0.0984
H	3.00	3.50	0.1181	0.1378
I	8.00	10.00	0.3150	0.3937
J	4.90	5.10	0.1929	0.2008
K	1.90	2.10	0.0748	0.0827
J	4.90	5.10	0.1929	0.2008
K	1.90	2.10	0.0748	0.0827
L	3.50	4.00	0.1378	0.1575
M	4.75	5.25	0.1870	0.2067
N	2.00	3.00	0.0787	0.1181
O	0.55	0.75	0.0217	0.0295
P	TYP 5.08		TYP 0.2000	
Q	1.20	1.30	0.0472	0.0512